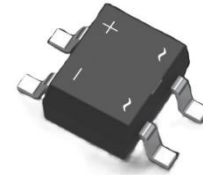


Fast Recovery Bridge Rectifier

Features

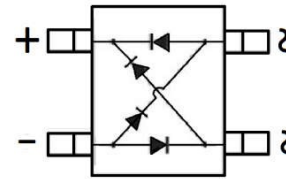
- Glass Passivated Chip Junction
- Reverse Voltage : 200 to 1000V
- Forward Current : 0.5A/0.8A
- High Surge Current Capability
- High temperature soldering : 260°C/10s at terminals



MBS

Applications

- High-frequency switching power supply
- PFC circuit



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

| Parameter | | Symbol | FMB2S | FMB4S | FMB6S | FMB8S | FMB10S | Unit |
|---|------------------------------|----------------|---------------|-------|-------|---------------|-------------|------|
| Maximum Repetitive Peak Reverse Voltage | | V_{RRM} | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | | V_{RMS} | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | | V_{DC} | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current | On glass-epoxy P.C.B.(Note1) | $I_{F(AV)}$ | 0.5 | | | | A | |
| | On aluminum substrate(Note2) | | 0.8 | | | | | |
| Peak Forward Surge Current 8.3mS single half sine wave superimposed on rated load(JEDEC method) | | I_{FSM} | 30 | | | | A | |
| Maximum Instantaneous Forward Voltage @0.4A | | V_F | 1.3 | | | | V | |
| Maximum DC Reverse Current at Rated DC Blocking Voltage | $T_A=25^{\circ}C$ | I_R | 5.0 | | | | μA | |
| | $T_A=125^{\circ}C$ | | 100 | | | | | |
| Maximum Reverse Recovery Time $T=25^{\circ}C$ (Note 3) | | T_{RR} | 150 | 250 | 500 | | nS | |
| Typical Junction Capacitance(Note 1) | | C_J | 25 | | | | pF | |
| Typical Thermal Resistance(Note 2) | $R_{\theta JA}$ | 28 | | | | $^{\circ}C/W$ | | |
| | $R_{\theta JC}$ | 85 | | | | | | |
| Operating Junction Temperature Range | | T_J, T_{stg} | (-55 to +150) | | | | $^{\circ}C$ | |

Notes:

1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.
2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05x0.05"(1.3x1.3mm) solder pad.
3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2x0.2"(5x5mm) copper pads.
4. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG.1 - Typical forward current derating curve

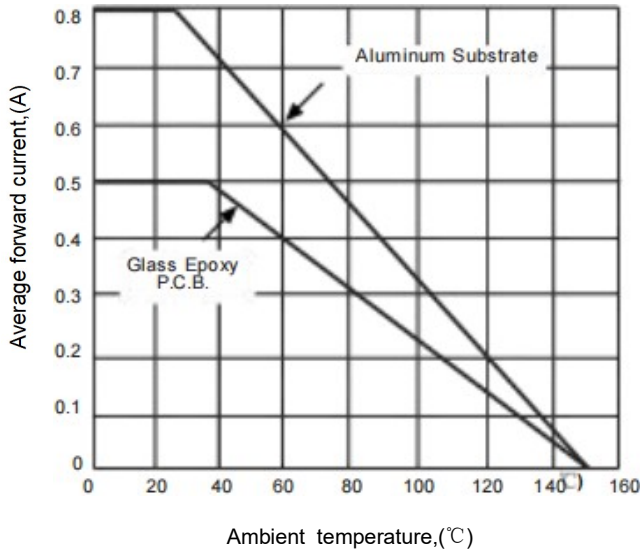


FIG.2 - Maximum non-repetitive peak forward surge current

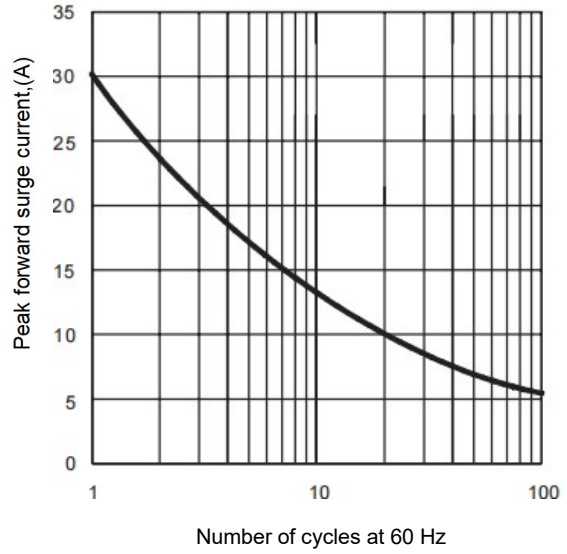


FIG.3 - Typical instantaneous forward characteristics

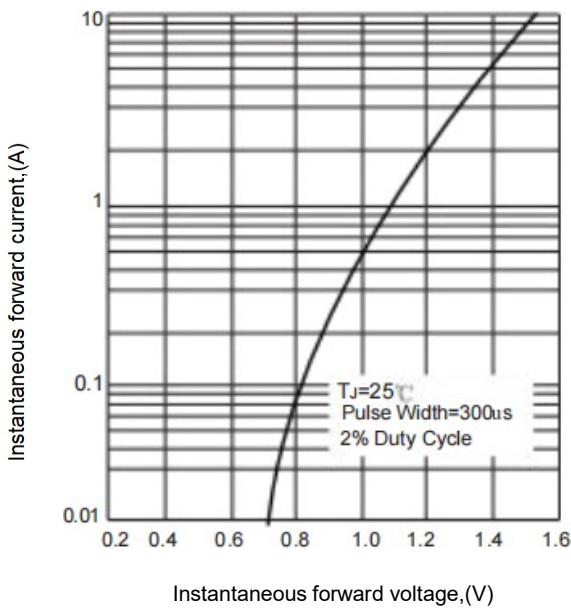
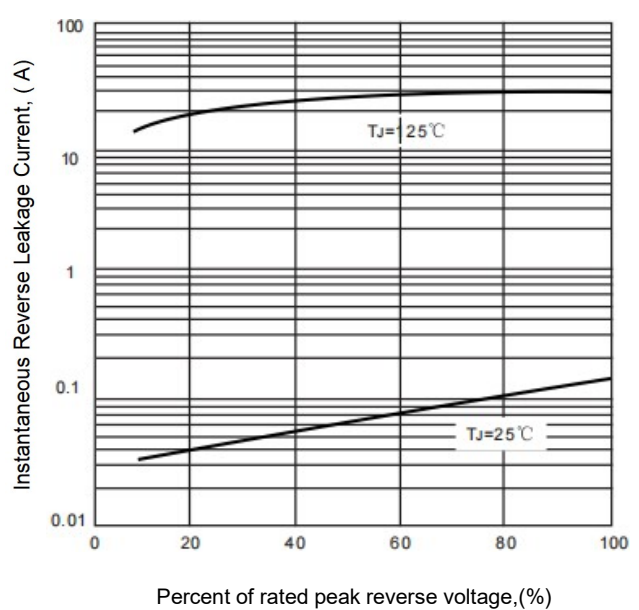
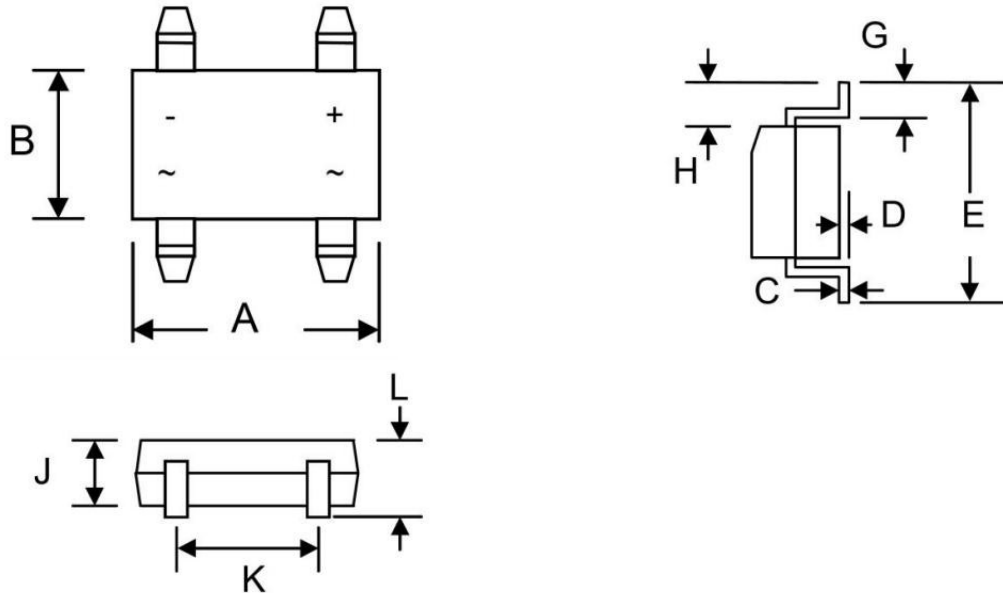


FIG.4 - Typical reverse characteristics



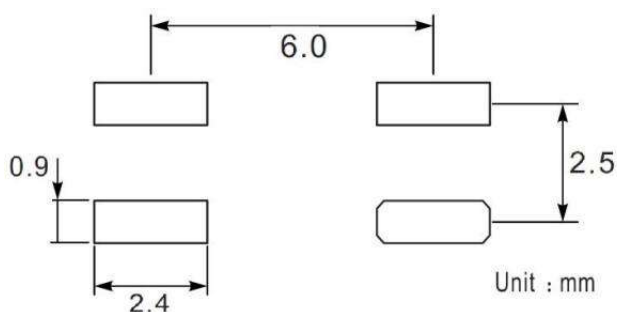
Package Outlines (Dimensions in mm)

Plastic surface mounted package(MBS)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.50 | 4.90 | 0.177 | 0.193 |
| B | 3.80 | 4.20 | 0.150 | 0.165 |
| C | 0.15 | 0.35 | 0.006 | 0.014 |
| D | ----- | 0.20 | --- | 0.008 |
| E | ----- | 7.00 | --- | 0.276 |
| G | 0.70 | 1.10 | 0.028 | 0.043 |
| H | 1.30 | 1.70 | 0.051 | 0.067 |
| J | 2.30 | 2.70 | 0.091 | 0.106 |
| K | 2.30 | 2.70 | 0.091 | 0.106 |
| L | --- | 3.00 | --- | 0.118 |

The recommended mounting pad size



Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

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